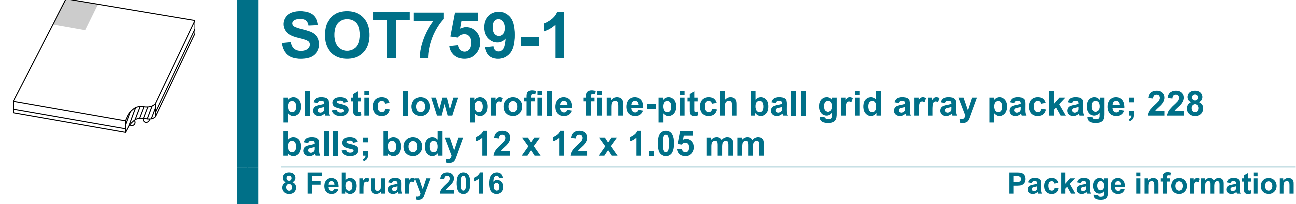


SOT759-1

plastic low profile fine-pitch ball grid array package; 228 balls; body 12 x 12 x 1.05 mm

8 February 2016 — Package information

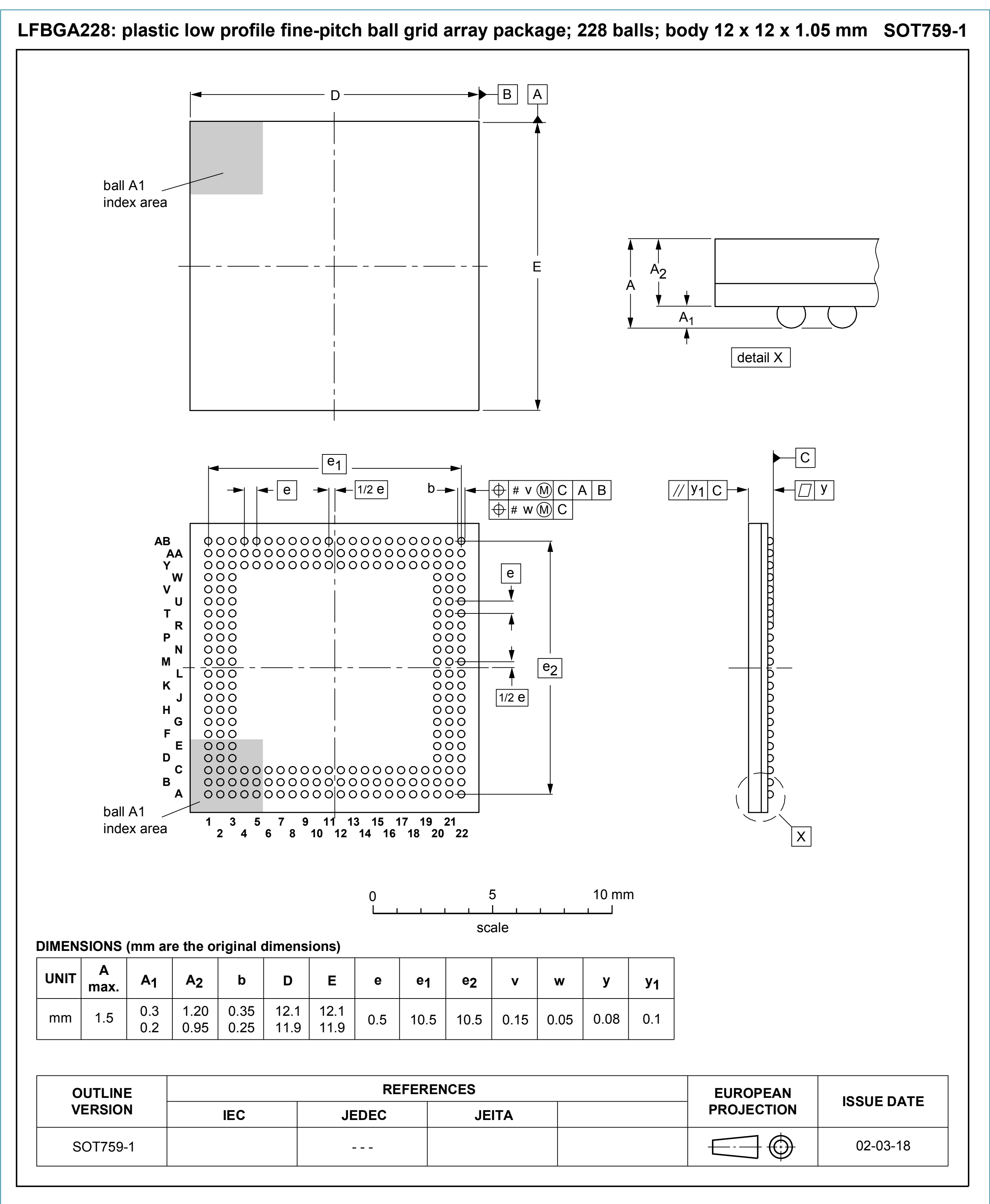
1. Package summary

Terminal position code	B (bottom)
Package type descriptive code	LFBGA228
Package type industry code	LFBGA228
Package style descriptive code	LFBGA (low profile fine-pitch ball grid array)
Package style suffix code	NA (not applicable)
Package body material type	P (plastic)
Mounting method type	S (surface mount)
Issue date	18-3-2002

Table 1. Package summary

Symbol	Parameter		Min	Typ	Nom	Max	Unit
D	package length		11.9	-	12	12.1	mm
E	package width		11.9	-	12	12.1	mm
A	seated height		[tbd]	-	1.5	1.5	mm
A_2	package height		0.95	-	1.05	1.2	mm
n_2	actual quantity of termination		-	-	228	-	

2. Package outline



DIMENSIONS (mm are the original dimensions)

UNIT	A max.	A_1	A_2	b	D	E	e	e_1	e_2	v	w	y	y_1
mm	1.5	0.3 0.2	1.20 0.95	0.35 0.25	12.1 11.9	12.1 11.9	0.5	10.5	10.5	0.15	0.05	0.08	0.1

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT759-1		- - -				02-03-18

Fig. 1. Package outline LFBGA228 (SOT759-1)

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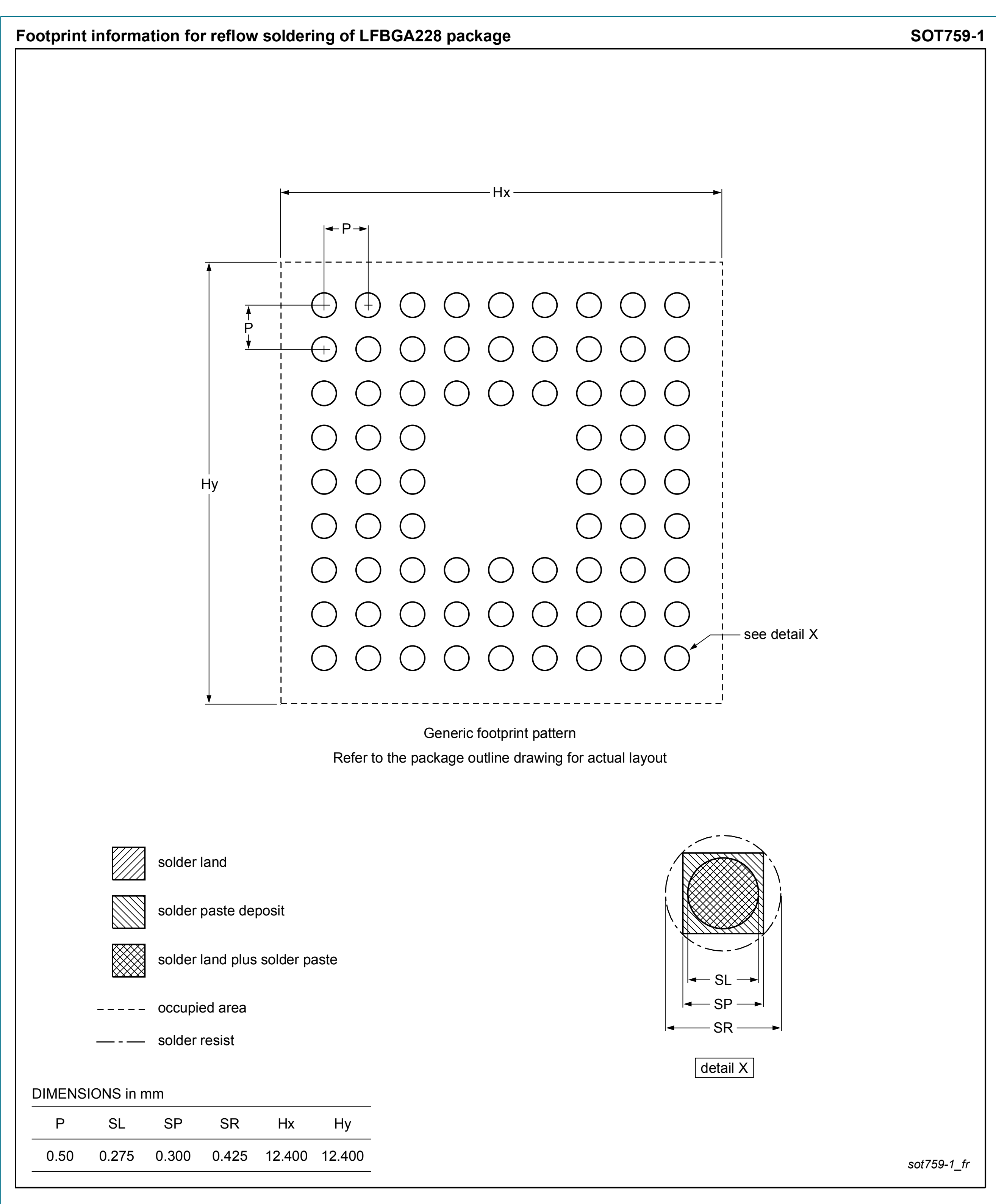
3. Soldering



DIMENSIONS in mm

P	SL	SP	SR	Hx	Hy
0.50	0.275	0.300	0.425	12.400	12.400

Fig. 2. Reflow soldering footprint for LFBGA228 (SOT759-1)

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5. Contents

1. Package summary... 1
2. Package outline.. 2
3. Soldering... 3
4. Legal information.. 4

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